

**IN THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. – 7 (Cancelled)

8. (Original)      An electronic device, comprising:

a substrate of insulating resin having at least a pair of interior terminal portions for connection upon an upper surface thereof;

an electronic element mounted on the terminal portions on the upper surface of said substrate, having at least a pair of electrode terminals thereof;

a frame member of insulating resin, bonded on the upper surface of said substrate, and having a cavity formed for storing said electronic element therein;

at least a pair of exterior terminal portions for connection, formed on an outer peripheral surface of said substrate, being electrically conducted to said interior terminals; and

a cover member of insulating material, for hermetically sealing over the cavity of said frame member, in which said electronic element is stored, wherein roughened surfaces are formed on metal electrode portions, which are formed on the upper surface of said substrate for electrically conducting said interior terminal portions to said exterior terminal portions, where said frame member is bonded thereupon.

9. (Original) An electronic device as defined in the claim 8, wherein the metal electrode portions forming said interior terminal portions, on which the roughened surfaces are formed to be bonded with said frame member, are made of copper.

10. (Original) An electronic device as defined in the claim 8, wherein said terminal portions for exterior connection are formed upon concave portions on side surfaces of said substrate, being provided extending from the upper surface to the lower surface thereof.

11. (Original) An electronic device as defined in the claim 8, wherein said terminal portions for exterior connection are formed upon concave portions on side surfaces of said substrate, being provided on corners extending from the upper surface to the lower surface thereof.

12. (Original) An electronic device as defined in the claim 8, wherein said substrate, said frame member and said cover member are formed from plate-like members of metal-clad laminate.

13. (Original) An electronic device as defined in the claim 8, wherein said electronic element stored within said cavity is an optical element, and said cover member for sealing over said cavity is made of transparent material.

14. (Currently Amended) A printed wiring board for use of the electronic devices according to the claim [[1]]8, comprising a plate made of insulating resin, and plural number of electrode portions for use of said terminals for interior connection, which are formed at or in vicinity of the electrode portions of plural number of the electronic devices to be mounted thereon.

15. (Original) A printed wiring board for use of the electronic devices, as defined in the claim 14, wherein said electrode portions are plated through-holes, which are formed on said insulating resin plate and are filled up with non-conductive resin therein.

16. – 19. (Cancelled)

20. (Original) A method for manufacturing an electronic device, comprising the following steps:

(a) forming at least a pair of terminal portions for interior connection, on an upper surface of a substrate of insulating resin;

(b) mounting an electronic element on the terminal portions for interior connection, on the upper surface of said substrate;

(c) bonding a frame member of insulating resin on the upper surface of said substrate, so as to form a cavity, in which said electronic element is stored; and

(d) bonding a cover member of insulating material on said frame member for hermetically sealing over the cavity thereof, in which said electronic element is stored, wherein in the step of said step (a), roughened surfaces are formed on metal

electrodes, which are provided for electrically conducting said terminal portions for interior connection to an outside thereof, where said frame member is bonded thereon.

21. – 23. (Cancelled)

24. (Currently Amended)      An electronic device as defined in the claim ~~24~~8, wherein ~~the exterior terminal~~terminal portions for connection, being electrically connected with said ~~internal~~interior terminal portion, are provided on a lower surface of said substrate.

25. (Currently Amended)      An electronic device as defined in the claim ~~24~~8, wherein conductors formed on said substrate, exposing to said cavity and the outside are made from layers of noble metal.

26. – 28. (Cancelled)